

BYV30W-600P Ultrafast power diode

Rev.01 - 26 June 2017

Product data sheet

1. General description

Ultrafast power diode in a SOD142 (2-lead TO247) plastic package.

2. Features and benefits

- Fast switching
- Very low on-state loss
- Low leakage current
- Low thermal resistance

3. Applications

- Active PFC in air conditioner
- S.M.P.S Power Factor Correction (PFC)
- Half-bridge / full-bridge switched-mode power supplies

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values		Unit		
Absolute	maximum rating						
V_{RRM}	repetitive peak reverse voltage			600			V
$I_{F(AV)}$	average forward current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 129 °C; Fig. 1; Fig. 2; Fig. 3		30			A
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 µs; T _{mb} ≤ 129 °C; square-wave pulse		6	60		А
I _{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4		290			A
		t_{p} = 8.3 ms; $T_{\text{j(init)}}$ = 25 °C; sine-wave pulse;	330		А		
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static ch	aracteristics	·					
V _F	forward voltage	I _F = 30 A; T _j = 25 °C; <u>Fig. 6</u>		-	1.18	1.55	V
		I _F = 30 A; T _j = 150 °C; <u>Fig. 6</u>		-	0.98	-	V
Dynamic	characteristics		· ·				
t _{rr}	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 50 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; \text{ Fig. 7}$		-	42	75	ns
		$I_F = 30 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$		-	65	-	ns
		$I_F = 30 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_i = 125 \text{ °C}; Fig. 7$		-	101	-	ns

5. Pinning information

Table 2.	Pinning info	rmation		
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	К	cathode		K — A 001aaa020
2	А	anode		001888020
mb	mb	mounting base; connected to cathod	1 2 TO-247 (SOD142)	

6. Ordering information

Table 3. Ordering information						
Type number Package						
	Name	Description	Version			
BYV30W-600P	TO-247	Plastic Single-ended through-hole package; Heatsink mounted; 1 mounting hole; 2-lead TO-247	SOD142			

7. Marking

Table 4. Marking codes							
Type number	Marking codes						
BYV30W-600P	BYV30W-600P						

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V _{RRM}	repetitive peak reverse voltage		600	V
V _{RWM}	crest working reverse voltage		600	V
V _R	reverse voltage	DC	600	V
I _{F(AV)}	average forward current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 129 °C; Fig. 1; Fig. 2; Fig. 3	30	A
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 μs; T _{mb} ≤ 129 °C; square-wave pulse	60	A
I _{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	290	A
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse;	330	А
T _{stg}	storage temperature		-55 to 175	°C
T _j	junction temperature		175	°C

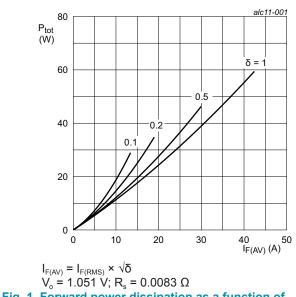
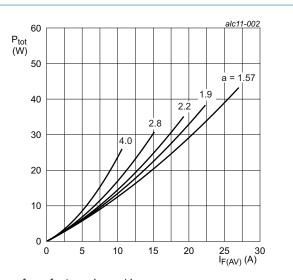
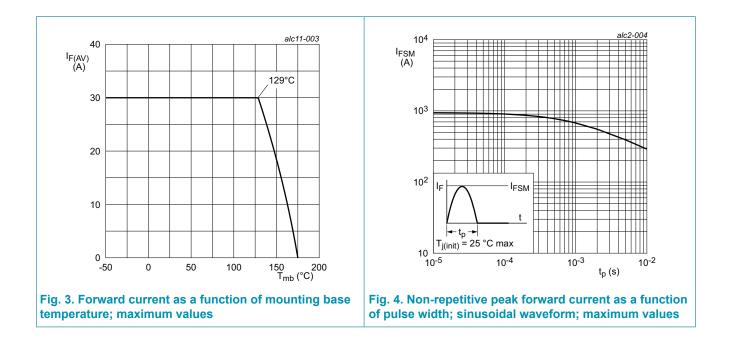


Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



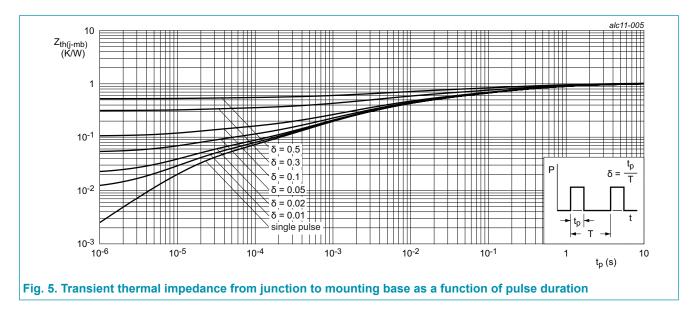
a = form factor = $I_{F(RMS)}/I_{F(AV)}$ Vo = 1.051 V; Rs = 0.0083 Ω Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

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9. Thermal characteristics

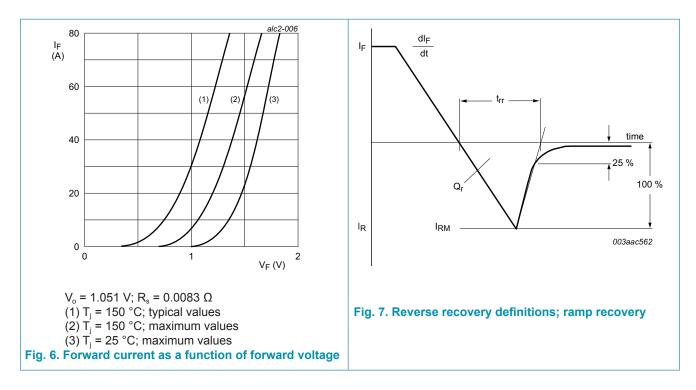
Table 6. Th	ermal characteristics					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<u>Fig. 5</u>	-	-	1	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	45	-	K/W



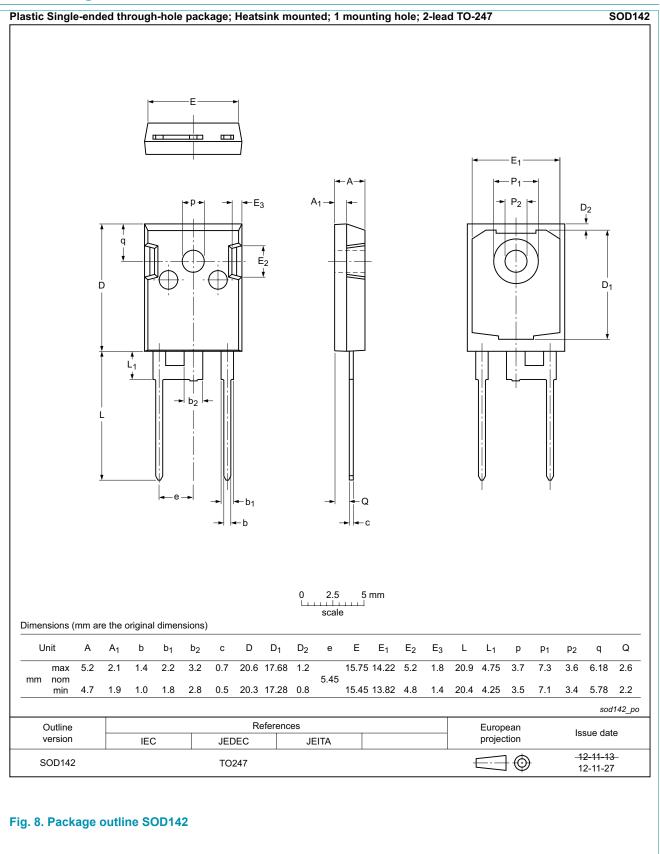
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10. Characteristics

Table 7. Cl	haracteristics					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
V _F	forward current	I _F = 30 A; T _j = 25 °C; <u>Fig. 6</u>	-	1.18	1.55	V
		I _F = 30 A; T _j = 150 °C; <u>Fig. 6</u>	-	0.98	-	V
I _R	reverse current	V _R = 600 V; T _j = 25 °C	-	2	10	μA
		V _R = 600 V; T _j = 125 °C	-	-	500	μA
Dynamic	characteristics					
Q _r	reverse charge	$I_F = 30 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	272	-	nC
		I _F = 30 A; V _R = 400 V; dI _F /dt = 200 A/µs; T _j = 125 °C; <u>Fig. 7</u>	-	775	-	nC
t _{rr}	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 50 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	42	75	ns
		$I_F = 30 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	65	-	ns
		I _F = 30 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 125 °C; <u>Fig. 7</u>	-	101	-	ns
I _{RM}	peak reverse recovery current	$I_F = 30 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	8.4	-	A
		I _F = 30 A; V _R = 400 V; dI _F /dt = 200 A/μs; T _j = 125 °C; <u>Fig. 7</u>	-	15.2	-	A



11. Package outline



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12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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- [2] The term 'short data sheet' is explained in section "Definitions".
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